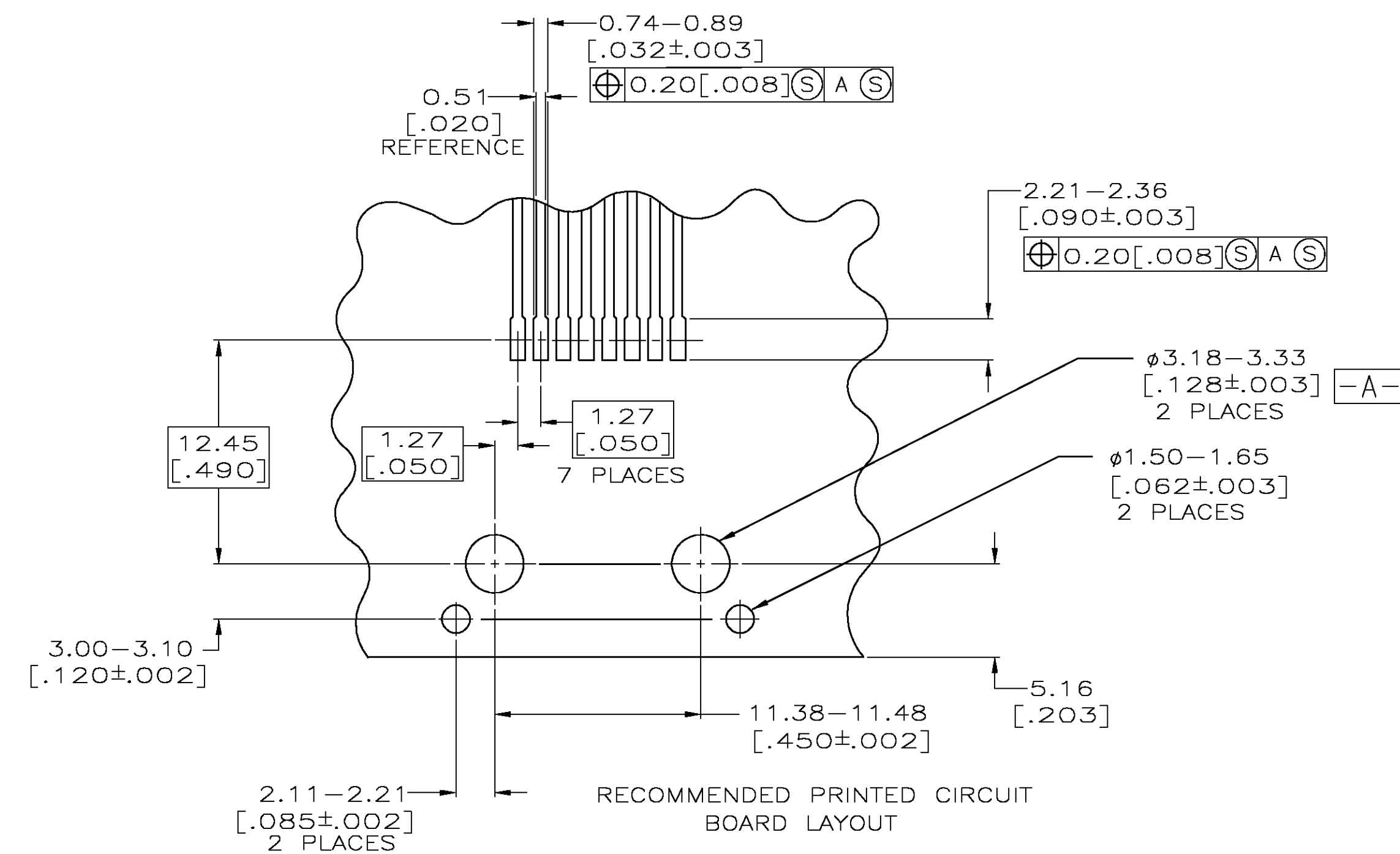
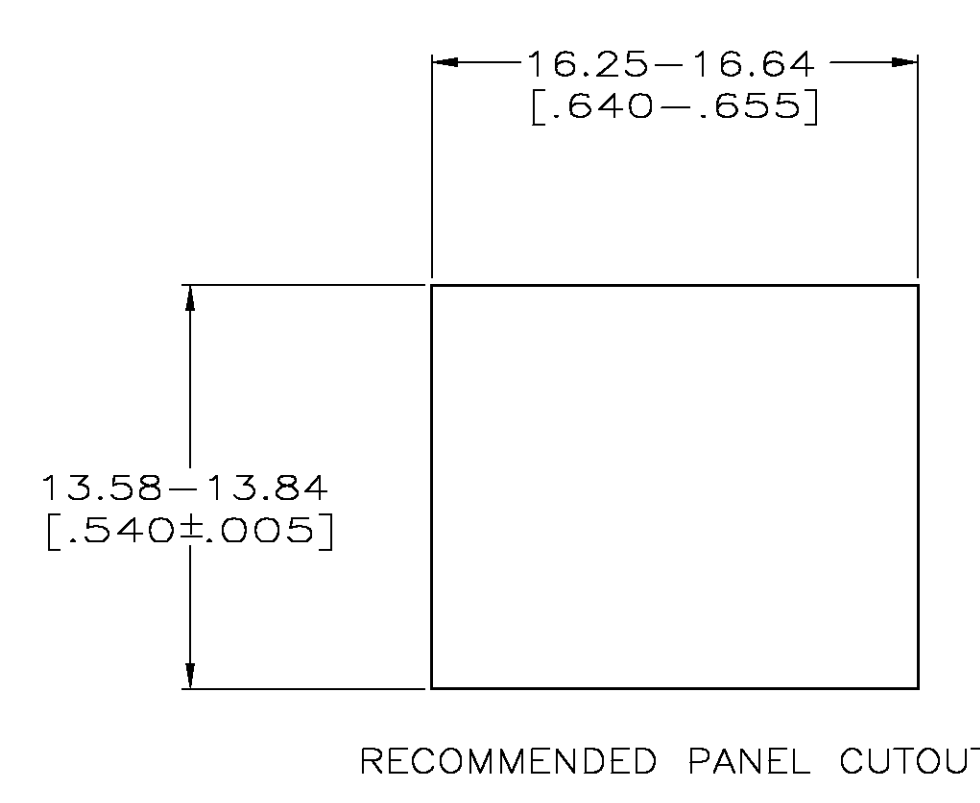
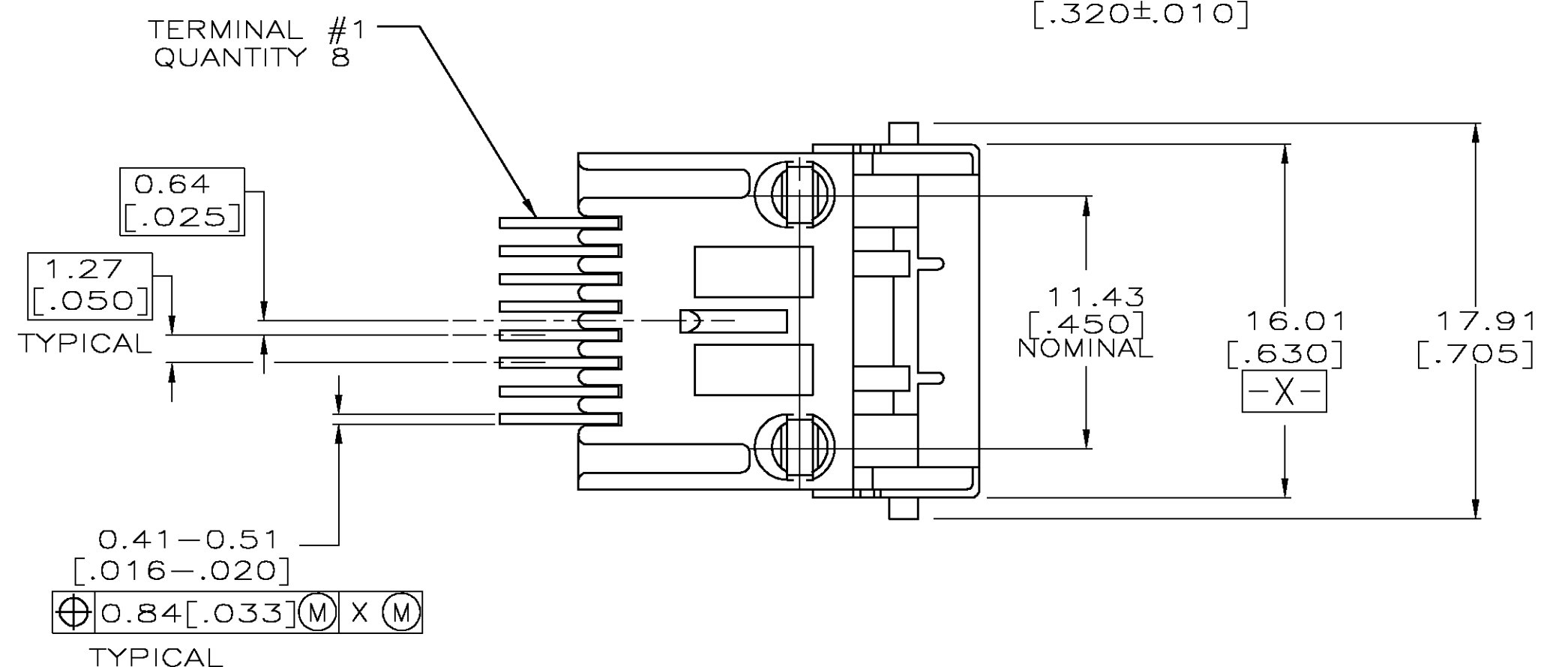
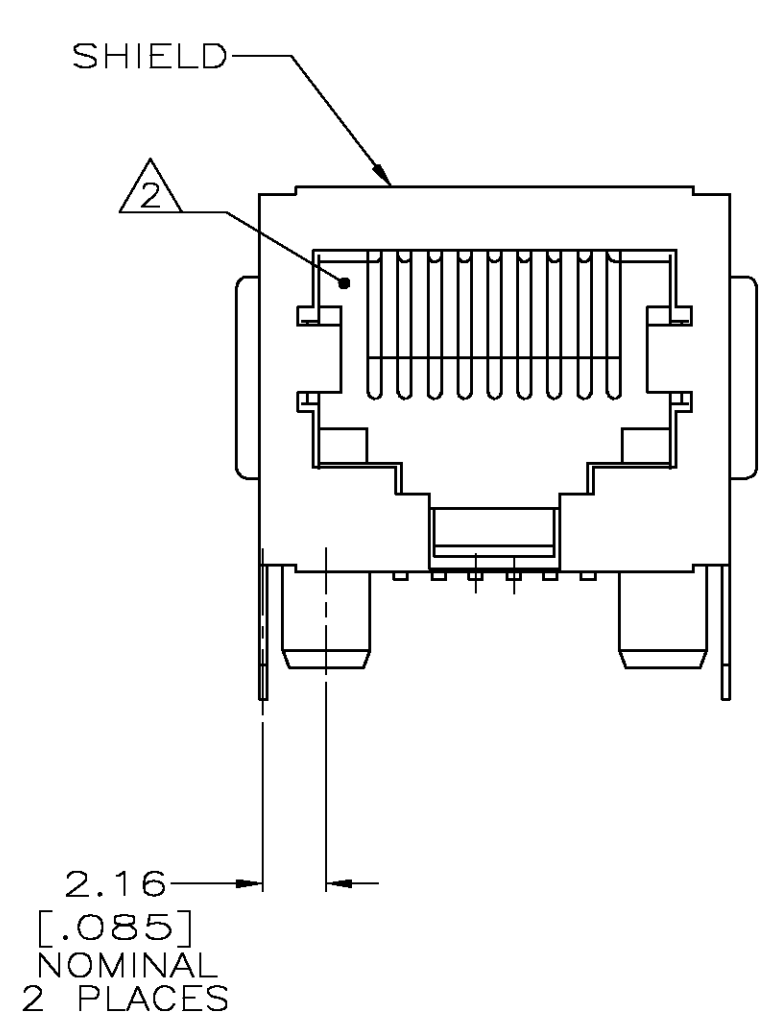
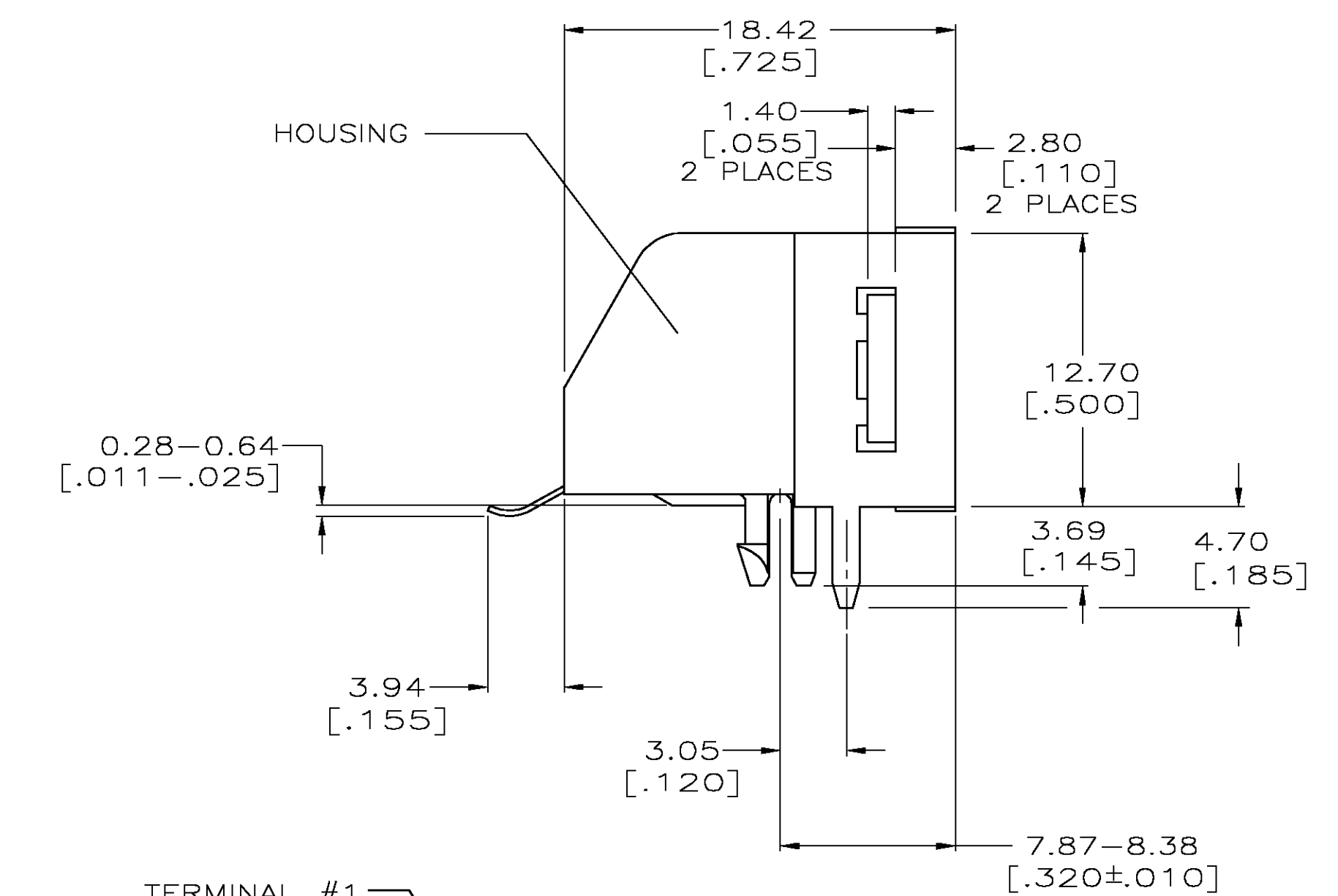


| LOC | | DIST | | REVISONS | | DATE | APPD |
|-----|---|------|---|----------|-----|---------------------------|------|
| GP | 0 | P | F | ZONE | LTR | DESCRIPTION | JTB |
| | | | | F | | RLSD -2 ; EC 0511-0234-03 | BK |



- △ MATERIAL: HOUSING - HTN MOLDING COMPOUND, 94 VO, BLACK.
 TERMINAL- 0.36 [.014] THICK PHOS-BRONZE PLATE WITH 1.27µm [.000050] THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [.000150] THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm [.000050] THICK NICKEL UNDERPLATE.
 SHIELD- 0.25 [.010] THICK COPPER ALLOY, PLATE WITH 2.03µm [.000080] THICK TIN-LEAD.
- △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
- 3. DIMENSIONS ARE MAXIMUM UNLESS OTHERWISE SPECIFIED.
- 4. SNAP-IN RETENTION FEATURE ACCOMMODATES 1.44-1.71 [.062±.005] THICK PRINTED CIRCUIT BOARD.
- △ PACKAGING TAPE AND REEL: (PER EIA 481 SPECIFICATION)
 TAPE: 44 [1.73] WIDE
 POCKET DEPTH: 17.65 [.695]
 POCKET PITCH: 32 [1.26]
 CLEAR PSA TAPE TRAILER 160 [6.30] MIN LENGTH
 PLASTIC REEL DIA. 330 [13.0]
 PIECES PER REEL: 100

| | |
|----------------|----------|
| △ TAPE & REEL | 558178-2 |
| TRAY | 558178-1 |
| PACKAGING TYPE | PART NO. |

| | | |
|--|----------------------------|---|
| DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN mm [INCHES] TOLERANCES ON : 2 PLC DEC ± - 3 PLC DEC ± - ANGLES ± - | DR 7-15-93 B. SIMPSON | NAME MODULAR JACK ASSEMBLY, 8 POSITION, RIGHT ANGLE, SURFACE MOUNTING, SHIELDED, LOW PROFILE, PRINTED CIRCUIT BOARD GROUND AND PANEL STOPS |
| | CHK 7-23-93 C. WHITT | |
| MATERIAL | APPD 7-28-93 J. TONEY | PRODUCT SPEC 108-1163 |
| | APPD 7-28-93 H. MCGRATH | APPLICATION SPEC 114-6040 |
| FINISH | | SIZE D |
| | | CAGE CODE 00779 |
| | | DRAWING NO 558178 |
| | | SCALE 4:1 |
| | | SHEET 10F 1 |

THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.